**KPHF-1612QBDSURKZGC**

1.6 x 1.26 mm SMD Chip LED Lamp

DESCRIPTIONS

- The Blue source color devices are made with InGaN Light Emitting Diode
- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

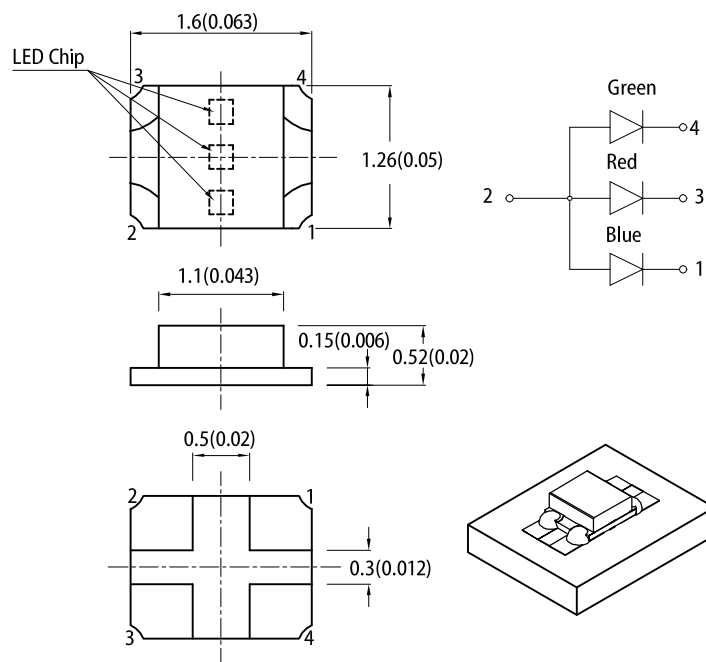
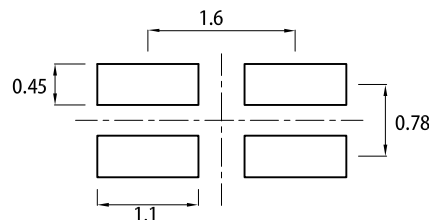
- 1.6 x 1.26 mm SMD LED, 0.52 mm thickness
- Low power consumption
- Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

- Backlight
- Status indicator
- Home and smart appliances
- Wearable and portable devices
- Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

**PACKAGE DIMENSIONS****RECOMMENDED SOLDERING PATTERN**(units : mm; tolerance : ± 0.1)**Notes:**

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
KPHF-1612QBDSURKZGC	Blue (InGaN)	Water Clear	40	70	140°
			*40	*70	
	Hyper Red (AlGaInP)		120	200	
			*40	*80	
	Green (InGaN)		400	600	
			*400	*600	

Notes:1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.2. Luminous intensity / luminous flux: $\pm 15\%$.

* Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ _{peak}	Blue Hyper Red Green	460 645 515	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Blue Hyper Red Green	465 630 525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Blue Hyper Red Green	25 28 30	-	nm
Capacitance	C	Blue Hyper Red Green	100 35 45	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Blue Hyper Red Green	3.3 1.95 3.3	4 2.5 4.1	V
Reverse Current (V _R = 5V)	I _R	Blue Hyper Red Green	-	50 10 50	μA

Notes:

1. The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

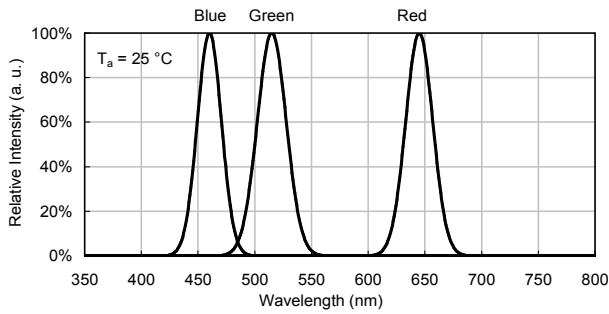
Parameter	Symbol	Value			Unit
		Blue	Hyper Red	Green	
Power Dissipation	P _D	120	75	102.5	mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	T _j	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +85			°C
DC Forward Current	I _F	30	30	25	mA
Peak Forward Current	I _{FM} ^[1]	150	185	150	mA
Electrostatic Discharge Threshold (HBM)	-	250	3000	450	V

Notes:

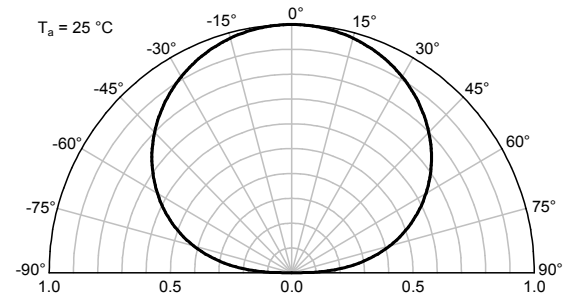
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

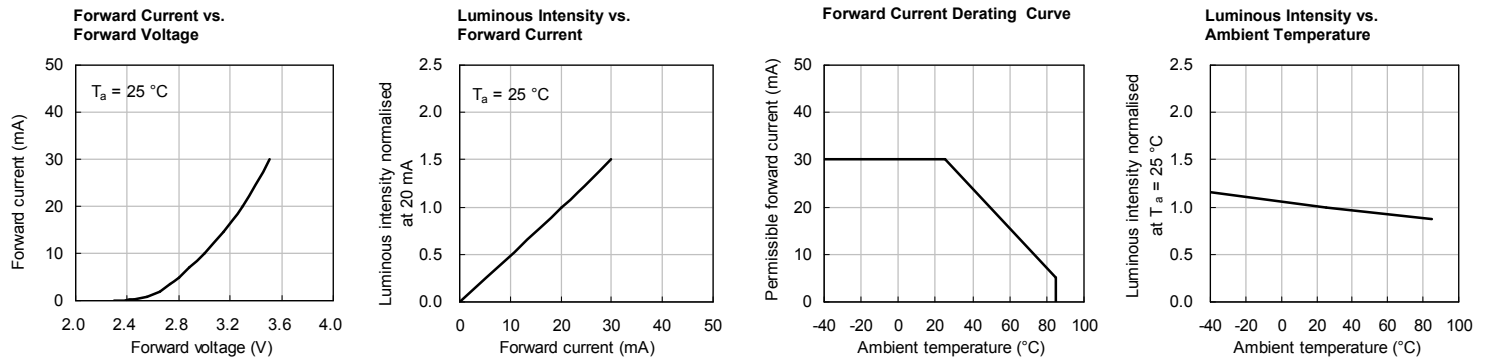
RELATIVE INTENSITY vs. WAVELENGTH



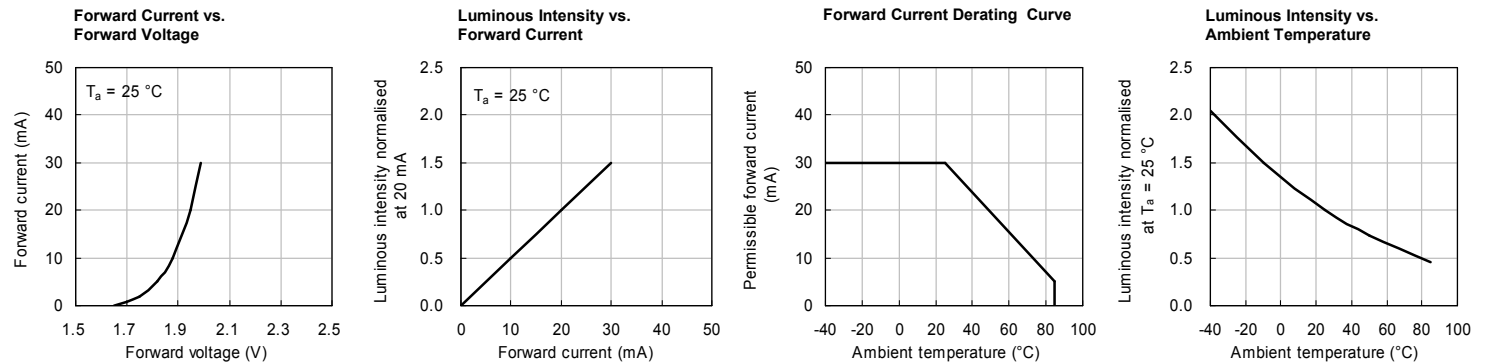
SPATIAL DISTRIBUTION



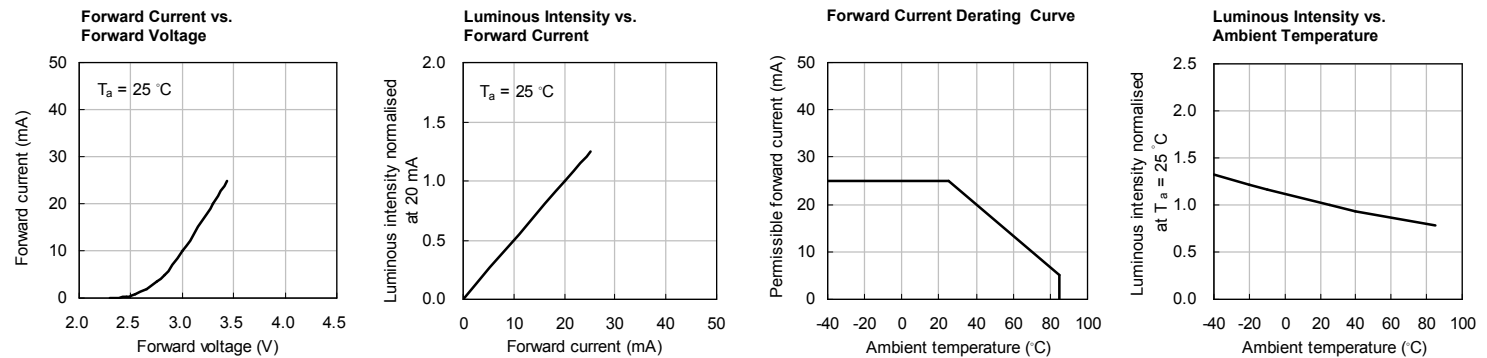
BLUE



HYPER RED

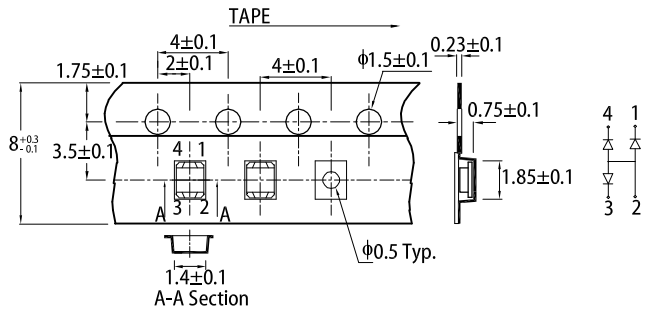
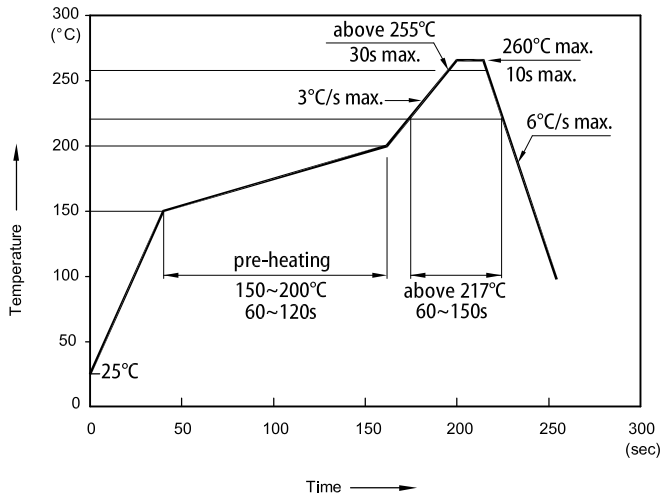


GREEN

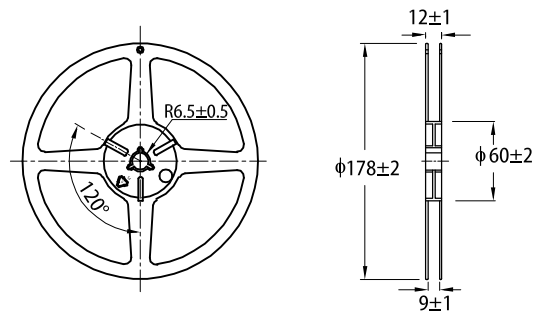


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

TAPE SPECIFICATIONS (units : mm)



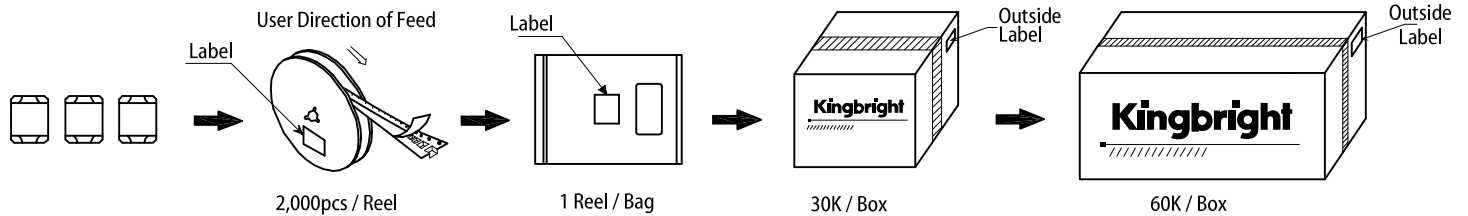
REEL DIMENSION (units : mm)



Notes:

1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



Kingbright
 PINO: XXXXXXXX
 QTY: XXXXXpcs
 SIN: XXXX
 CODE: XX
 COUNTRY: CN
 LOT NO:
 (SP)XXXXXXXXXX

XXXXXXXX-XXXX
 QC DATE: XXX XX XXXX PASSED
 RoHS Compliant

PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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